

Application No. 09/09/746,774

IN THE SPECIFICATION:

Please substitute the following amended paragraph for the pending paragraph on page 10, beginning at line 16:

Turning now to Figure 7, a perspective view of the process step of Figure 6 is shown. As shown, all of the components of both PWB 4 and PWB 5 can be assembled and completed prior to the separating and/or tilting step. Moreover, complete circuit and functional testing of individual boards PWB 4 and PWB 5 can be completed simultaneously, thereby avoiding inventory and handling expenses and problems. Such testing is exemplified by testing fixture 60 shown in Figure 5 because connectors 11-14 are already inserted on single substrate board 2 prior to separation or tilting, then the entire PWB assembly of both boards can be completely circuit and functionally tested prior to separation. This is a major advantage over the prior art since, as discussed above, such combined testing normally cannot be completed until after each board is separately manufactured, inventoried, handled, retrieved, and inserted in a socket fixture. Under the prior art, when the combination of boards fails a test, the correction process must both determine whether the defect occurred in the connecting and fixturing process or whether a defect occurred on one of the boards due to mishandling during handling and assembly. In the process of the present invention, testing need occur only once on both the individual and the connected combination of boards.

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Please substitute the following amended paragraph for the pending paragraph on page 20, beginning at line 2:

B2 The process of the present invention enables more efficient manufacture and assembly of interconnected printed wiring boards by: forming multiple circuits upon a common substrate before the common substrate is separated into separate boards; making interconnections between the separate boards before the boards are separated; and separating the common substrate into a plurality of separate interconnected boards. Using the inventive process, interconnections between boards can be fully tested on a single substrate and inventory and handling processes relating to joining of separate boards can be simplified or eliminated.
